

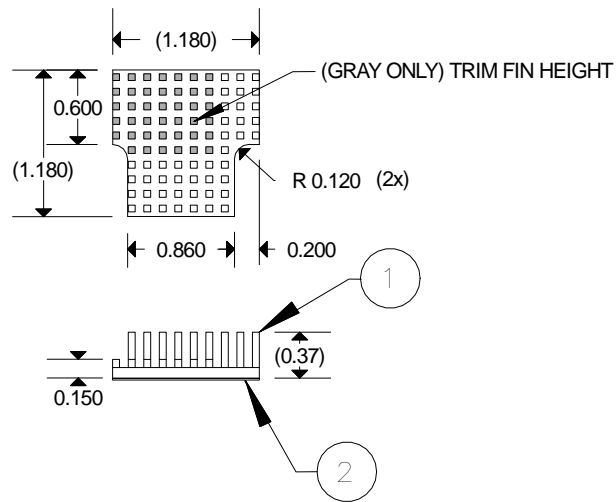
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DWG NO	6880551	SHT	1	REV	A
REVISIONS					
REV	DESCRIPTION	DATE	DRAWN	APPROVED	
1	INITIAL RELEASE	4-01-09	MFT		
A	PROD RELEASE	4-08-09	KRM		



## NOTES:

1. MATERIAL: (ALUMINUM)
2. FINISH: RE-ANODIZED AFTER PART MODIFICATION.  
COLOR: BLACK
3. BREAK SHARP EDGES AND DEBURR.
4. APPLY THERMAL PAD AND TRIM TO HEATSINK PART OUTLINE.
5. PACKAGING: PACKAGE EACH COMPLETED PART INDIVIDUALLY TO PRESERVE AESTHETIC APPEARANCE AND PREVENT MECHANICAL DEFORMATION DURING SHIPMENT AND STORAGE.
6. PERMANENTLY MARK INDIVIDUALLY PACKAGED PART WITH PART NUMBER AND CURRENT REV LETTER IN 0.12 MINIMUM TALL CHARACTERS.
7. REMOVAL OF EXISTING THERMAL PAD SUPPLIED WITH HEATSINK ITEM 1 MUST BE DONE PRIOR TO RE-ANODIZING.

**ALL COMPONENTS AND MATERIALS MUST BY RoHS COMPLIANT.**

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2	HEATPAD, CPU, 1.375 X 1.375 X 0.005 THK w/PSA	BERGQUIST CPU PAD (DIGKEY BER135-ND)	1	EA	
1	HEATSINK, 30mm x 30mm x 9.4mm BGA	AAVID 335824B00034G	1	EA	
ITEM	DESCRIPTION	MFR NAME and P/N	QTY	UM	NOTE
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES		DO NOT SCALE DRAWING			
±0.015 BEND TO A BEND ±0.010 FEATURE TO A BEND ±0.010 FEATURE TO AN EDGE ±0.005 FEATURE TO A FEATURE ±0.5 DEGREE FOR ANGLE		APPROVALS		DATE	
		DRAWN MFT		4-01-09	
		CHECKED			
MATERIAL		DIAMOND SYSTEMS CORPORATION			
SEE NOTES		HELIOS VGA HEATSINK			
FINISH		SIZE B	DWG NO	REV	
SEE NOTES		B	6880551	A	
		SCALE	DOC REV: B	THIRD ANGLE PROJECTION	SHEET 1 of 1

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